

1. (Twice Amended) A semiconductor assembly comprising:

a support structure having a top surface, wherein said support structure is a film; and

(C1) at least one semiconductor die having a perimeter, including four sides, and a top and bottom surface, said bottom surface having a smaller area than said top surface of said support structure, said at least one semiconductor die being secured at its bottom surface to said top surface of said support structure by a flowable adhesive material which does not extend past any one of the sides of said perimeter of said at least one semiconductor die.

15. (Twice Amended) A semiconductor assembly comprising:

(C2) a first semiconductor die having a top and a bottom surface;  
a second semiconductor die having a perimeter, including four sides, and a top and bottom surface, said bottom surface having a smaller area than said top surface of said first semiconductor die, said second die being secured at its bottom surface to said top surface of said first semiconductor die by a flowable adhesive material which does not extend past any one of the sides of said perimeter of said second semiconductor die; and  
wherein said top surface of said first semiconductor die has at least one electrical contact area positioned at a location exterior to said perimeter of said second

C2 semiconductor die, and wherein a distance between said electrical contact area and said perimeter of said second semiconductor die is less than or equal to about 428 microns.